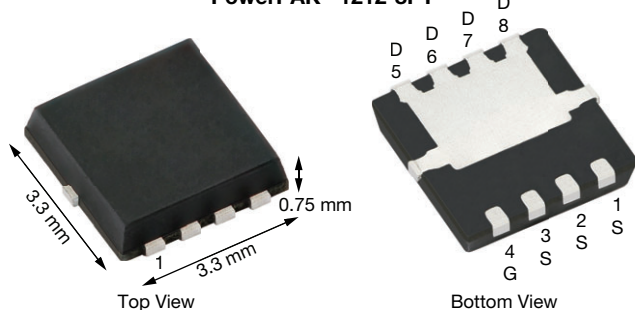


N-Channel 30 V (D-S) MOSFET

PowerPAK® 1212-8PT


FEATURES

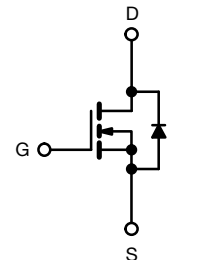
- TrenchFET® Gen IV power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- High power density DC/DC
- Synchronous rectification
- VRMs and embedded DC/DC
- Battery protection



N-Channel MOSFET

PRODUCT SUMMARY

V _{DS} (V)	30
R _{DS(on)} max. (Ω) at V _{GS} = 10 V	0.0043
R _{DS(on)} max. (Ω) at V _{GS} = 4.5 V	0.0060
Q _g typ. (nC)	10
I _D (A)	87 ^a
Configuration	Single

ORDERING INFORMATION

Package	PowerPAK 1212-8PT
Lead (Pb)-free and halogen-free	SiSA12BDN-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V _{DS}	30	V
Gate-source voltage	V _{GS}	+20, -16	V
Continuous drain current (T _J = 150 °C)	I _D	T _C = 25 °C	87
		T _C = 70 °C	70
		T _A = 25 °C	24 ^{b, c}
		T _A = 70 °C	19 ^{b, c}
Pulsed drain current (t = 100 μs)	I _{DM}	150	A
Continuous source-drain diode current	I _S	T _C = 25 °C	47
		T _A = 25 °C	3.7 ^{b, c}
Single pulse avalanche current	I _{AS}	16	A
Single pulse avalanche energy	E _{AS}	13	mJ
Maximum power dissipation	P _D	T _C = 25 °C	52
		T _C = 70 °C	33
		T _A = 25 °C	4 ^{b, c}
		T _A = 70 °C	2.6 ^{b, c}
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^{d, e}		260	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SMYBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{b, f}	R _{thJA}	25	31	°C/W
Maximum junction-to-case (drain)	R _{thJC}	1.9	2.4	°C/W

Notes

- Based on T_C = 25 °C
- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8PT is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 63 °C/W



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30	-	-	V
Drain-source breakdown voltage ^(c) (transient)	V _{DSt}	V _{GS} = 0 V, I _{D(aval)} = 70 A, t _{transient} ≤ 50 ns	36	-	-	
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = 250 μA	-	20	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	-5.1	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.2	-	2.4	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +20, -16 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	
On-state drain current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	25	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A	-	0.0027	0.0043	Ω
		V _{GS} = 4.5 V, I _D = 7 A	-	0.0048	0.0060	
Forward transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 20 A	-	67	-	S
Dynamic ^b						
Input capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	-	1470	-	pF
Output capacitance	C _{oss}		-	545	-	
Reverse transfer capacitance	C _{rss}		-	60	-	
C _{rss} /C _{iss} ratio			-	0.040	0.080	
Total gate charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A	-	21	32	nC
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	-	10	15	
Gate-source charge	Q _{gs}		-	4.2	-	
Gate-drain charge	Q _{gd}		-	2.6	-	
Output charge	Q _{oss}	V _{DS} = 15 V, V _{GS} = 0 V	-	15	-	
Gate resistance	R _g	f = 1 MHz	0.3	1.4	2.8	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = 15 V, R _L = 1.5 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	-	10	20	ns
Rise time	t _r		-	20	40	
Turn-off delay time	t _{d(off)}		-	15	30	
Fall time	t _f		-	10	20	
Turn-on delay time	t _{d(on)}	V _{DD} = 15 V, R _L = 1.5 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	-	16	35	
Rise time	t _r		-	31	60	
Turn-off delay time	t _{d(off)}		-	12	25	
Fall time	t _f		-	12	25	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	47	A
Pulse diode forward current ^a	I _{SM}		-	-	150	
Body diode voltage	V _{SD}	I _S = 10 A	-	0.75	1.1	V
Body diode reverse recovery time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	-	37	70	ns
Body diode reverse recovery charge	Q _{rr}		-	37	60	nC
Reverse recovery fall time	t _a		-	21	-	ns
Reverse recovery rise time	t _b		-	16	-	

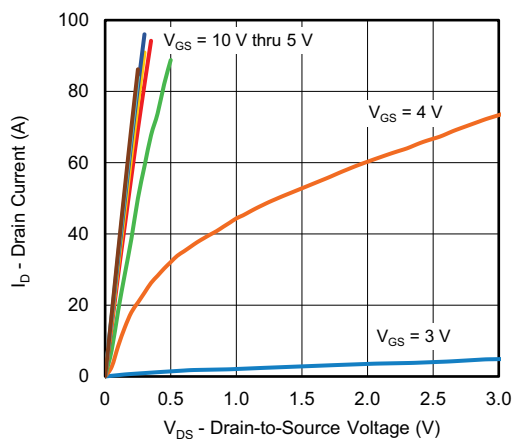
Notes

- a. Pulse test: pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing
c. Based on characterization, not subject to production testing

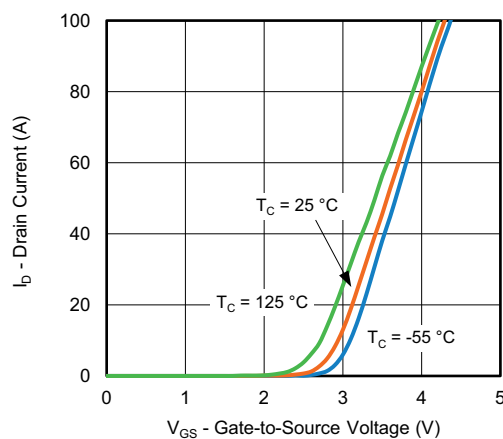
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



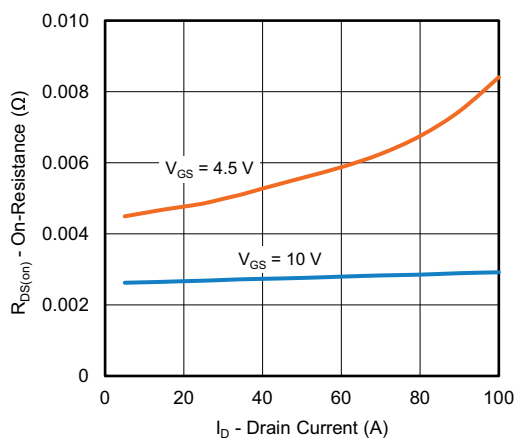
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



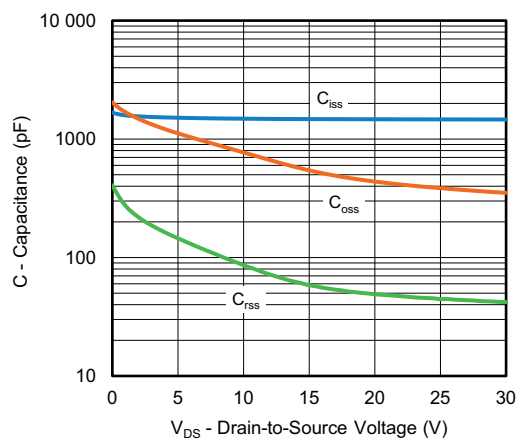
Output Characteristics



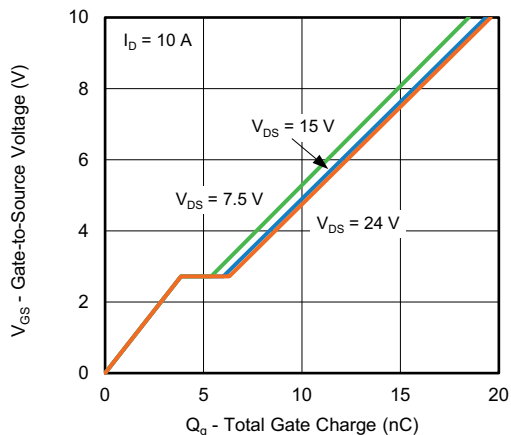
Transfer Characteristics



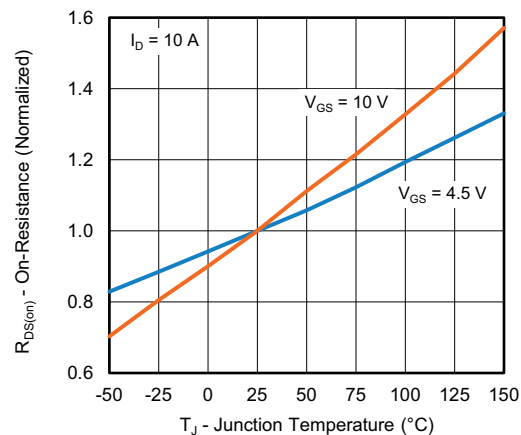
On-Resistance vs. Drain Current



Capacitance



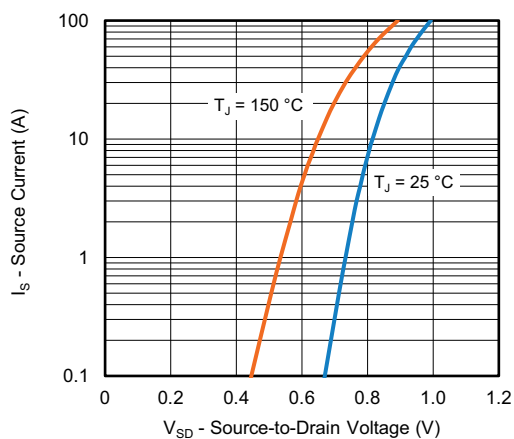
Gate Charge



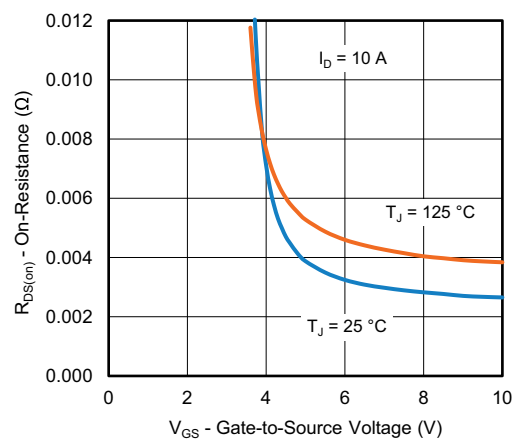
On-Resistance vs. Junction Temperature



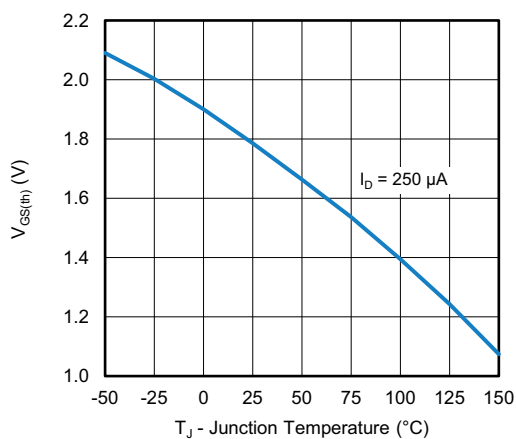
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



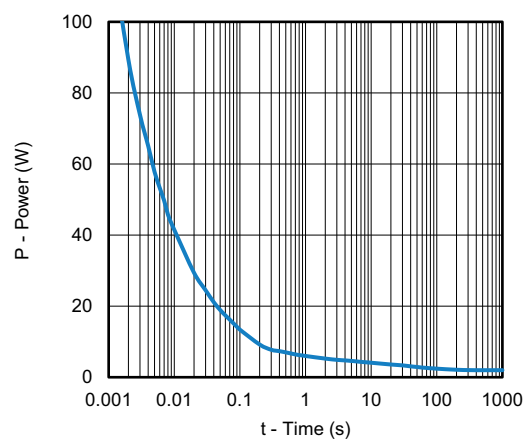
Source-Drain Diode Forward Voltage



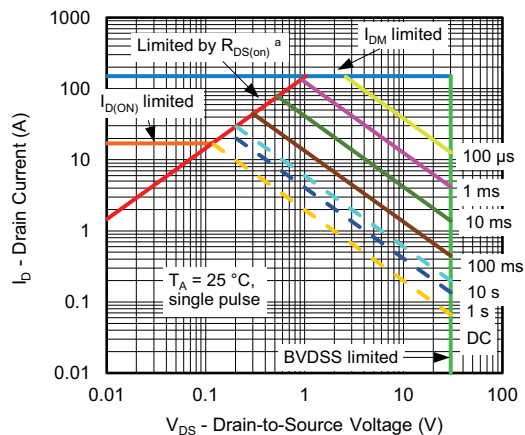
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



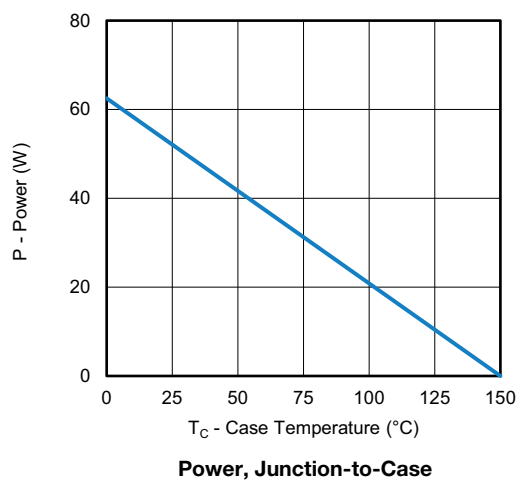
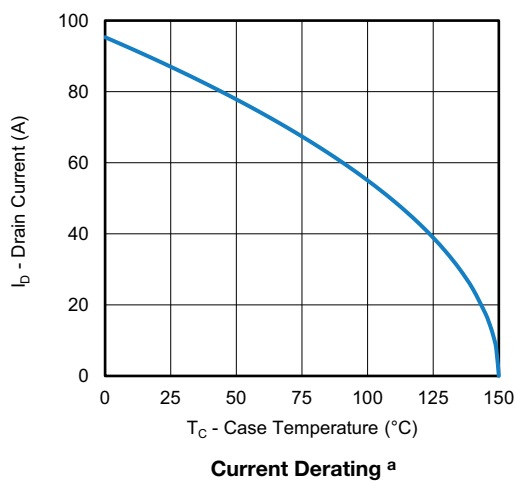
Single Pulse Power, Junction-to-Ambient



Safe Operating Area



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

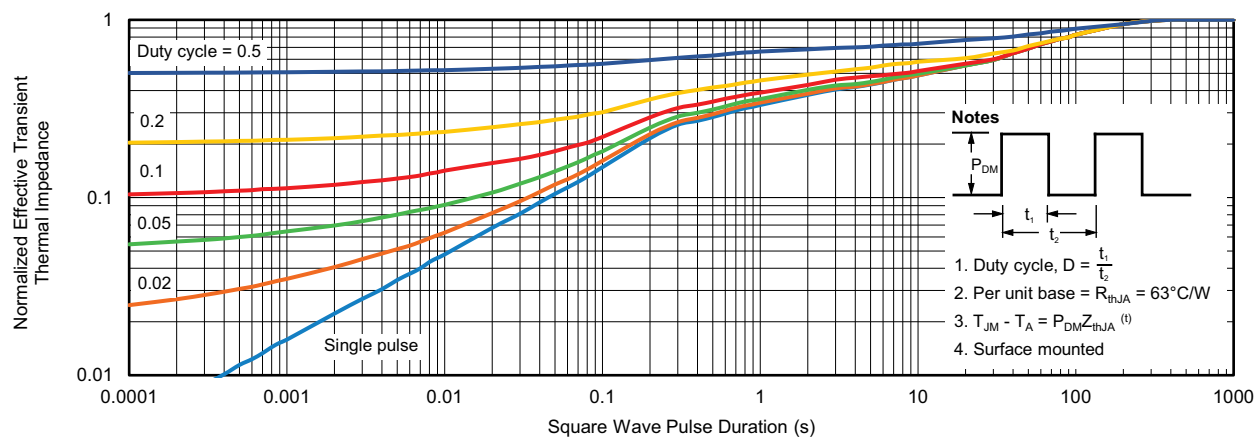


Note

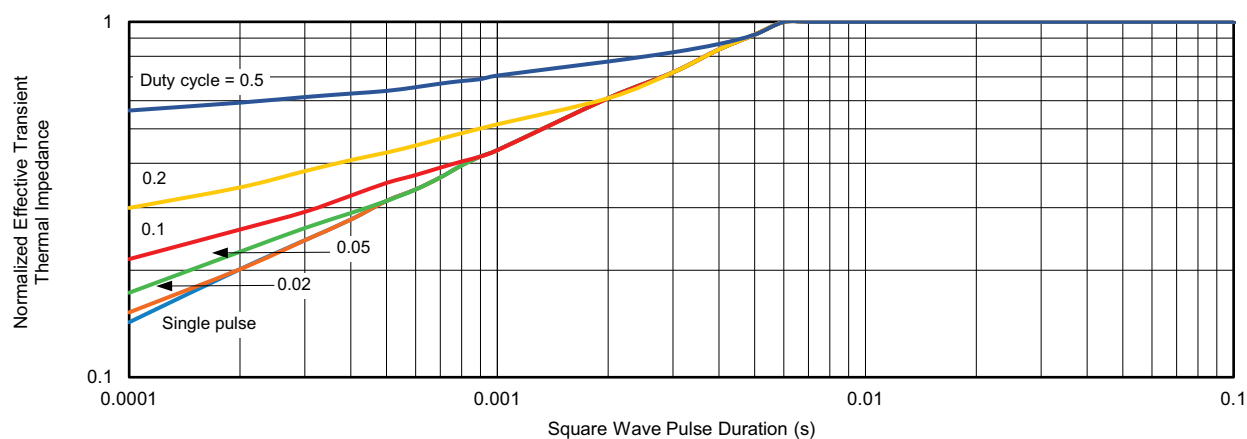
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



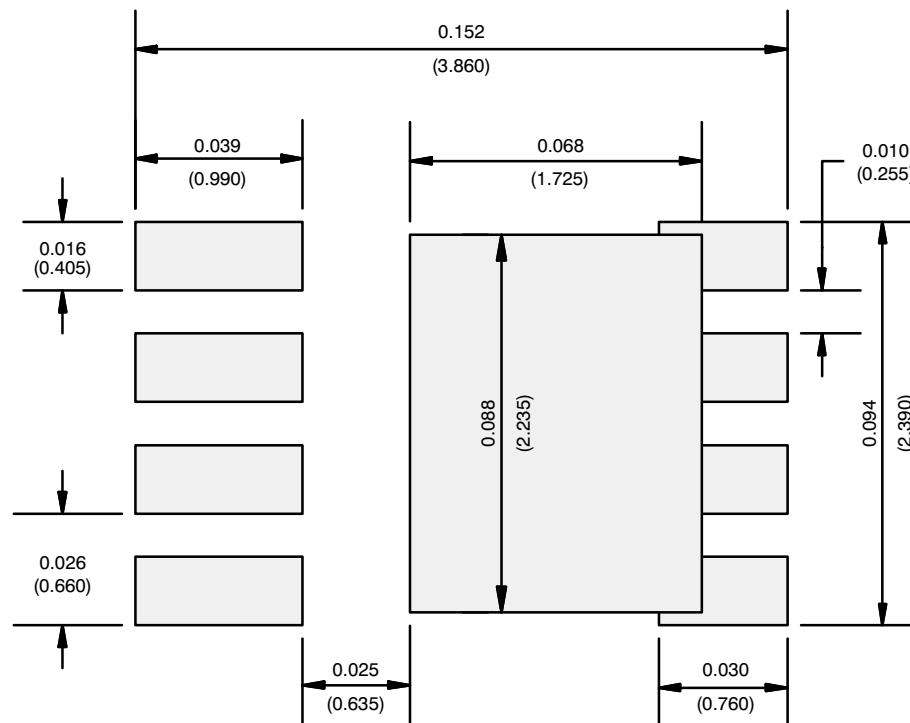
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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